FOR THE MEDIA

ASMPT Announces Gordon Lam as Chief Commercial Officer for SEMI Solutions

Tech industry veteran brings extensive global leadership experience to accelerate commercial growth

Billerica (USA), September 8, 2025 – ASMPT, the world's leading provider of integrated hardware and software solutions for semiconductor and electronics manufacturing, today announced the appointment of Mr. Gordon Lam as Chief Commercial Officer for Semiconductor Solutions (SEMI Solutions).

Gordon joined ASMPT in August with over 25 years of key leadership experience in various global technology and enterprise solutions organizations. As Chief Commercial Officer for SEMI Solutions, he is responsible for driving the commercial strategy for its strong semiconductor assembly and packaging solutions portfolio to accelerate growth across key market segments, while adding value to and strengthening customer relationships.

Most recently, Gordon served as Chief Revenue Officer, President, and Operating Committee Member at Syniti, where he led global go-to-market strategies and drove significant business transformation. He previously held senior leadership roles at NetApp, SAP, Computer Sciences Corporation, and Microsoft, bringing extensive experience across hardware, software, and enterprise solutions. With deep expertise in sales management, strategic planning, and operations, Gordon has a proven track record of delivering multi-year growth and profitability in highly competitive markets.

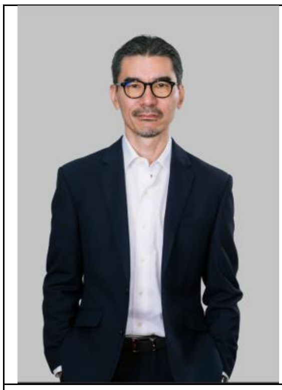
"Gordon's extensive commercial leadership experience and proven ability to drive growth in complex technology markets make him an ideal fit for ASMPT as we continue to capitalize on the strong demand dynamics in advanced packaging and AI-driven semiconductor applications," said Robin Ng, Chief Executive Officer of ASMPT. “His appointment reinforces our commitment to strengthening our commercial capabilities and deepening our customer partnerships globally."

"I'm thrilled to join ASMPT as Chief Commercial Officer at a pivotal moment for our industry. Our comprehensive semiconductor assembly and packaging solutions are an exceptional platform for customer success," explained Gordon. "With strong market demand for advanced semiconductor technologies, I am focused on strengthening customer partnerships and accelerating our commercial strategy, focusing on next-generation packaging and processing applications."

Gordon holds a dual degree in Electrical Engineering and Computer Science from UNSW and completed the Senior Executive Leadership Program at Stanford University. He is also a contributing member of the Forbes Technology Council.

Illustrations for downloading

The following print-ready artwork is available on the internet for downloading:
https://kk.htcm.de/press-releases/asmpt/



Gordon Lam, Chief Commercial Officer,
ASMPT Semiconductor Solutions

Image credit: ASMPT

About ASMPT Limited ("ASMPT")

ASMPT Limited is a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics. Headquartered in Singapore, ASMPT's offerings encompass the semiconductor assembly & packaging, and SMT (surface mount technology) industries, ranging from wafer deposition to the various solutions that organize, assemble and package delicate electronic components into a vast range of end-user devices, which include electronics, mobile communications, computing, automotive, industrial and LED (displays). ASMPT partners with customers very closely, with continuous investments in R&D helping to provide cost-effective, industry-shaping solutions that achieve higher productivity, greater reliability, and enhanced quality. ASMPT is a founding member of the Semiconductor Climate Consortium.

To learn more about ASMPT, please visit www.asmpt.com.

About ASMPT Semiconductor Solutions ("ASMPT SEMI")

ASMPT SEMI is the leading provider of forward-looking solutions for advanced packaging and semiconductor assembly. With its commitment to innovation and customer satisfaction, ASMPT SEMI offers a comprehensive range of products and services that meet the evolving needs of the microelectronics industry. Expert knowledge covers areas such as flip-chip and wafer-level packaging, advanced interconnect technologies, and more. ASMPT SEMI's state-of-the-art solutions enable customers to achieve higher performance, greater reliability, and improved cost-efficiency in the manufacturing of their semiconductor devices.

ASMPT SEMI sees itself as a pioneer and driving force of the Intelligence Revolution. With its advanced packaging and assembly technologies, the business segement creates the invisible connections that enable intelligent applications in Artificial Intelligence, Smart Mobility, and Hyperconnectivity.

For more information about ASMPT SEMI, visit semi.asmpt.com.

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